

COPPER FOIL FOR FINE PATTERN PRINTED CIRCUITS AND METHOD
OF PRODUCTION OF SAME

ABSTRACT OF THE DISCLOSURE

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Copper foil for fine pattern printed circuits having
a sufficient bond strength with a resin substrate,
eliminating the problems of residual copper, erosion at
the bottom portions of the circuit lines, etc. at the
10 time of formation of fine patterns, and superior in heat
resistance and electrical characteristics, comprising
untreated copper foil roughening treated on its surface,
wherein the untreated copper foil before roughening
treatment is an electrodeposited copper foil having a
15 surface roughness in terms of 10-point average roughness
Rz not more than 2.5 μm and a minimum distance between
peaks of rough pyramid of at least 5 μm or having further
crystal grains of an average particle size of not more
than 2 μm exposed at the surface thereof, and a method of
20 production of the same.